

**IN THE ABSTRACT**

Please rewrite the Abstract of the Disclosure as follows:

~~Attaining improvement of the reliability and standardization of the lead frame.~~ A semiconductor device comprises a plurality of inner leads extending around a semiconductor chip, a tape substrate-[5] supporting the semiconductor chip and joined to respective end portions of the inner leads, wires connecting the inner leads and pads formed on a main surface of the semiconductor chip, a seal portion formed by resin-sealing the semiconductor chip and the wires, and a plurality of outer leads linking in a line with the inner leads and protruded from the seal portion to the exterior of four directions. A relationship between a length (a) of a shorter side of the semiconductor chip and a clearance (b) from the semiconductor chip, to a tip of the inner leads arranged at the farthest location from the semiconductor chip is  $a \leq 2b$ . It is possible to attain a narrow pad pitch, and mount the semiconductor chip formed in a small size, and standardize the lead frame.

**IN THE SPECIFICATION**

Page 1, before the first line, add the paragraph:

--This is a continuation application of U.S. Serial No. 09/978,708, filed October 18, 2001.--